

John Scarpulla

Dr. John Scarpulla is a technical fellow at the The Aerospace Corporation. He has previously worked for RCA, GE, SAIC, Silicon Systems, TI, TRW, Northrup-Grumman. He holds a MSEE from Univ. of Pennsylvania (1981) , and BSEE and BS (Physics) from Villanova Univ. He has a Ph.D. from Cornell University (1988), where he researched submicron device physics simulation and nano-fabrication. Since then, he has been involved in solving problems in device physics, device packaging, radiation effects, and microwave devices. He has more than 150 publications and two patents. His current interests lie in the areas of reliability physics and statistics, GaN device physics, especially as related to space applications, and semiconductor device simulation.